

The documentation and process conversion measures necessary to comply with this amendment shall be completed by 26 January, 2001.

INCH POUND

MIL-PRF-19500/551C
AMENDMENT 2
26 October 2000
SUPERSEDING
AMENDMENT 1
10 December 1999

PERFORMANCE SPECIFICATION SHEET

SEMICONDUCTOR DEVICE, DIODE, SILICON, TRANSIENT VOLTAGE SUPPRESSOR
TYPES 1N6461 THROUGH 1N6468 AND 1N6461US THROUGH 1N6468US
JAN, JANTX, JANTXV, JANHC AND JANKC

This amendment forms a part of MIL-PRF-19500/551C, dated 12 September 1999 and is approved for use by all Departments and Agencies of the Department of Defense.

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* 3.4.3. Metallurgical bond construction. Add the following;

"3.4.3. Metallurgical bond construction. Devices shall be metallurgically bonded, thermally matched, noncavity-double plug construction in accordance with MIL-PRF-19500, and herein."

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4.3.2 Delete 4.3.2b and substitute:

"b. Read and record I_D and V_{BR} at T_A = room ambient as defined in the general requirements of MIL-STD-750. Remove defective devices, and record the number of failures."

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TABLE I, subgroup 4, conditions column, delete, "(see 4.5.1)" and substitute "(see 4.5.2b)".

TABLE I, subgroup 7, conditions column, delete, "(see 4.5.2)" and substitute "(see 4.5.2b)".

Changes from previous issue. The margins of this specification are marked with asterisks to indicate where changes from the previous issue were made. This was done as a convenience only and the Government assumes no liability whatsoever for any inaccuracies in these notations. Bidders and contractors are cautioned to evaluate the requirements of this document based on the entire content irrespective of the marginal notations and relationship to the last previous issue.

Custodians:
Army - CR
Navy - EC
Air Force - 11
NASA - NA
DLA - CC

Preparing activity:
DLA - CC

(Project 5961-2393)

Review activities:
Air Force - 13, 19